



HJ3055

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HJ3055 is designed for general purpose of amplifier and switching applications.

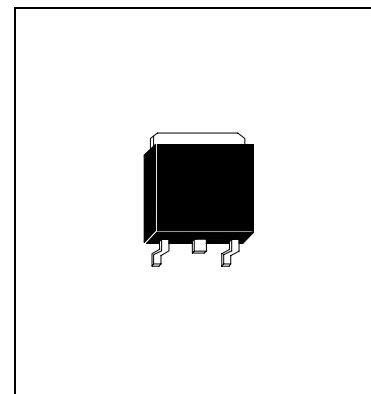
Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 70 V
BVCEO Collector to Emitter Voltage 60 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current 10 A
IB Base Current 6 A

Characteristics (Ta=25°C)

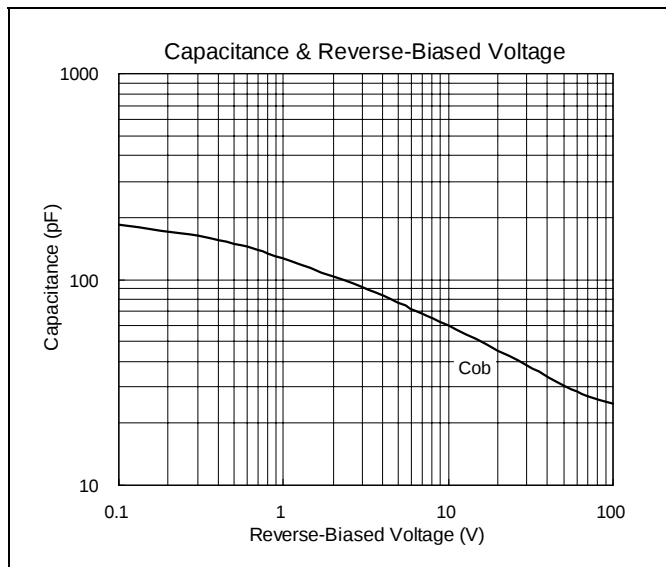
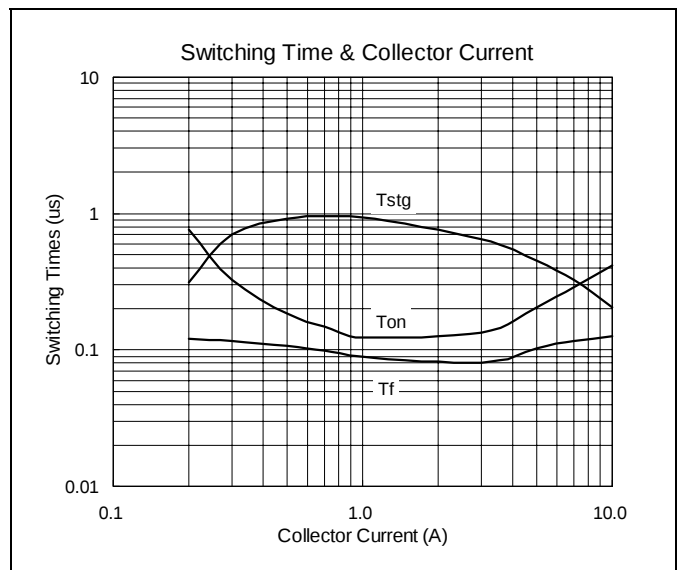
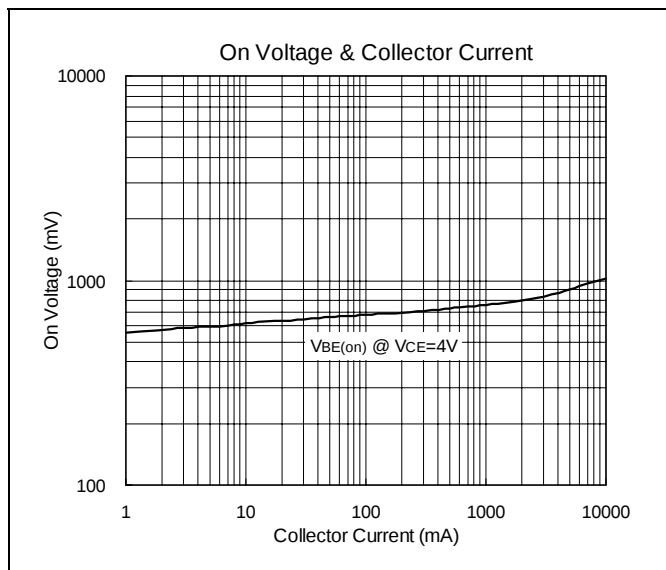
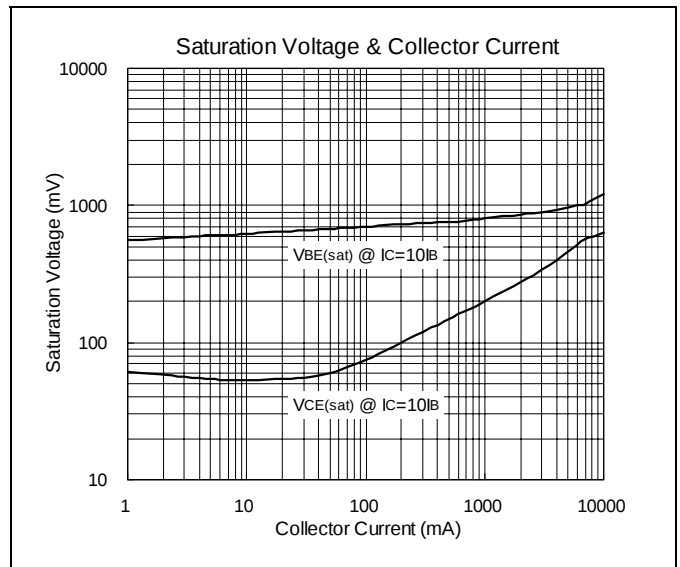
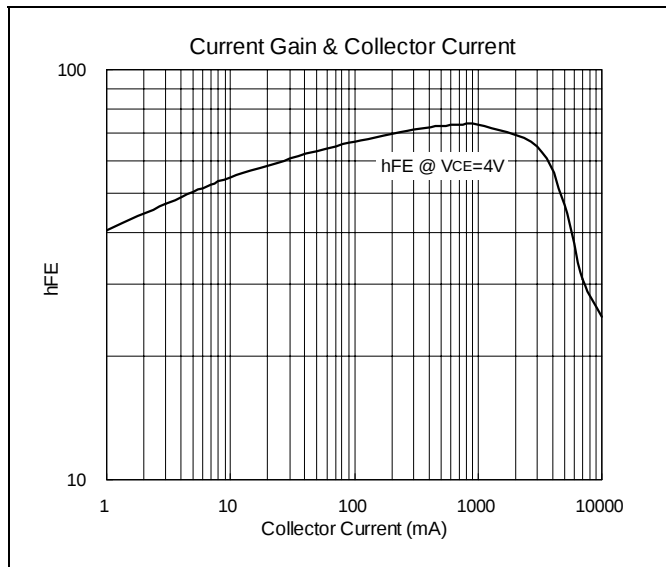
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	70	-	-	V	IC=30mA, IE=0
BVCEO	60	-	-	V	IC=1mA, IB=0
BVEBO	5	-	-	V	IE=1mA, IC=0
ICBO	-	-	20	uA	VCB=70V, IE=0
ICEX	-	-	20	uA	VCE=70V, VEB(off)=1.5V
ICEO	-	-	50	uA	VCE=30V, IB=0
IEBO	-	-	0.5	mA	VEB=5V, IC=0
*VCE(sat)1	-	-	1.1	V	IC=4A, IB=400mA
*VCE(sat)2	-	-	8	V	IC=10A, IB=3.3A
*VBE(on)	-	-	1.8	V	VCE=4V, IC=4A
*hFE1	20	-	100		VCE=4V, IC=4A
*hFE2	5	-	-		VCE=4V, IC=10A
fT	2	-	-	MHz	VCE=10V, IC=500mA, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



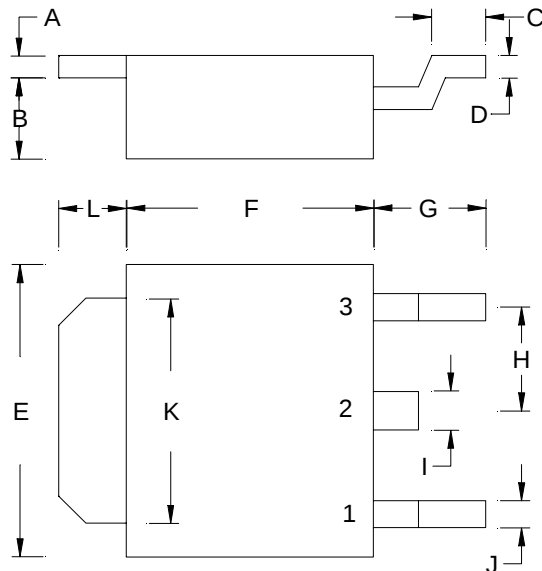


Characteristics Curve

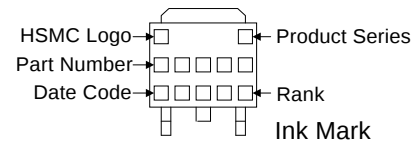




TO-252 Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-252 Plastic Surface Mount Package
HSMC Package Code : J

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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